Title: MICROSTRIP LINE DIELECTRIC OVERLAY

REMARKS

This responds to the Office Action mailed on <u>April 14, 2006</u>, and the references cited therewith.

No claims are amended, claims 19-34 have been cancelled, and no new claims are added; as a result, claims 1-4, 6-9, 11-15, and 17-18 remain pending in this application.

§112 Rejection of the Claims

Claims 1-4, 6, 7-9, 11, 12, 13-15, 17, 18, 20-22, 23-28, 30-32 and 34 were rejected under 35 U.S.C. § 112, second paragraph, for indefiniteness.

Claim 1 is believed to be appropriate and consistent as written. Consider as an example a substrate having a microstrip line 1mm above a ground plane, and having a .1mm conformal coating. If the coating over a microstrip line is .6mm, it is both greater than half the thickness of the substrate (.5mm), and greater than the average coating thickness across the circuit board (slightly over .1mm). Because the language appears plain and straightforward to understand and interpret as written, it has not been amended.

In claim 2, "varies in the same direction as" refers to positive or negative direction of variation. Given the descriptive context of variance above or below 1.0 in the same direction as another measurable dielectric constant, this claim is further believed to be clear as written, and applicant can't easily think of claim language that would make this more clear.

Claim 4 is intentionally not specific, and should also be interpreted as written. Because it recites "at least one of the microstrip lines", the connection points may be attached to any of the previously recited microstrip lines.

In claim 6, suggestion to replace "has a dielectric constant" with "has the dielectric constant thereof" appears to make a clearly understandable claim unclear, and has not been made.

In claim 18, average conformal coating thickness across the substrate is to be taken at its plain English meaning, i.e. conformal coating applied across the substrate necessarily has some characteristic average thickness, which can be measured or determined and is used as a point of reference here and in other claims.

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In claim 18, replacing "at least one" with "at least a first" would be unclear and make claim interpretation more difficult, as line 3 already recites "a first microstrip line" which could be misinterpreted as a limitation on the suggested claim language.

§102 Rejection of the Claims

Claims 1, 2, 13, 23-26, 28, 30 and 32 were rejected under 35 U.S.C. § 102(b) for anticipation by any one of Bruns (U.S. 5,982,249), Maschotta (German 131 327) and Anderson (U.S. 4,441,088).

Claims 6, 15, 27 and 34 were rejected under 35 U.S.C. § 102(b) for anticipation by either Maschotta or Anderson.

Claim 14 was rejected under 35 U.S.C. § 102(b) for anticipation by Maschotta.

Each of the pending claims contains a limitation, or depends from a claim containing a limitation, of a dielectric material thickness that is greater over at least one microstrip line than the average dielectric material thickness across the entire substrate or printed circuit board on which the microstrip line is formed. More specifically, the pending claims recite a coating that is thicker in the area over at least one microstrip line than the average coating thickness over the entire substrate, which is not found in any of the cited references.

Because this element is not found in the cited art as described above, these pending claims are also believed to be in condition for allowance. Reexamination and allowance of stillpending claims 1, 2, and 13, and of the claims that depend therefrom, is therefore respectfully requested.

§103 Rejection of the Claims

Claims 3, 4, 7-9 and 11 were rejected under 35 U.S.C. § 103(a) as being unpatentable over any one of Bruns, Maschotta and Anderson in view of Forbes et al. (U.S. 6,373,740).

Claim 12 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Maschotta or Anderson in view of Forbes et al.

Claims 17, 18, 20 and 21 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Bruns, Maschotta or Anderson in view of Adachi (U.S. 5,043,792).

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Claim 22 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Maschotta or Anderson in view of Adachi.

These claims either depend from or contain limitations of the claims rejected above under 35 U.S.C §102, and are allowable over the cited art for the reasons explained above. Reexamination and allowance of these claims is therefore respectfully requested.

CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance, and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 349-9581 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

ROY GREEFF

By his Representatives,

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Date July 14 06

Reg. No. 44,639

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this // day of June, 2006..

CANNON

Signature

Name